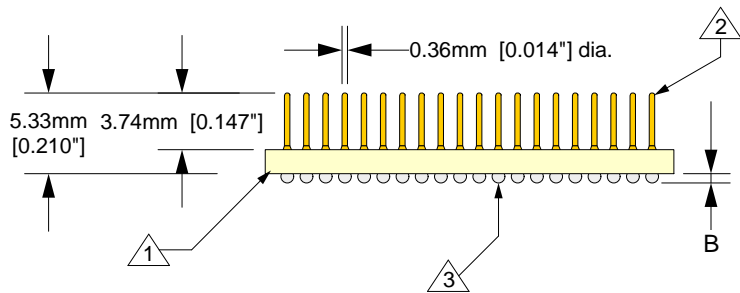


Top View  
(reference only)

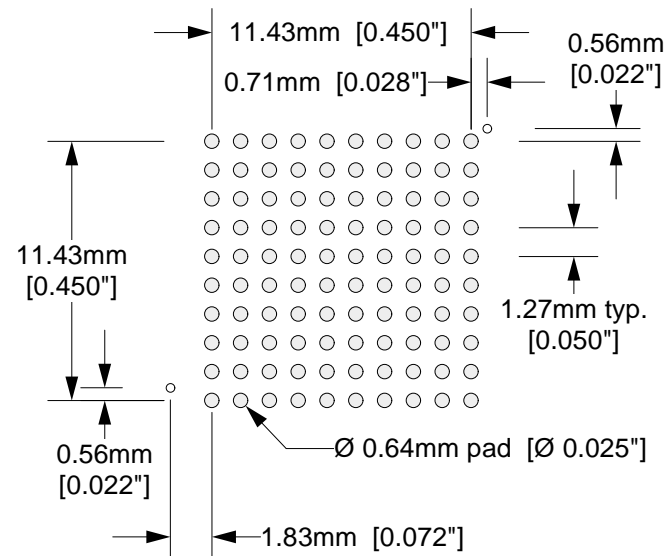


Side View  
(reference only)

**Note:** SMT foot is independent of actual BGA package thickness.

- 1 Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"] FR4/G10 or equivalent high temp material. Non-clad.
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 $\mu$ m [10 $\mu$ ] Au over 1.27 $\mu$ m [50 $\mu$ ] Ni (min.).
- 3 Balls: Eutectic 63/37 SnPb. Thermally isolated from terminal pins

Package Code: BGA100A




Top View: Recommended PCB Layout  
Scale: 3:1

Pin Count	100
Array Size	10X10
Pitch	1.27 mm[0.050"]
Perimeter size (XxY)	16.0mm[0.630"] x 16.0mm[0.630"]
MGA Location (CxD)	2.28mm[0.090"] x 2.28mm[0.090"]
Ball Thickness (B)	0.61mm[0.024"]

Description: BGA Emulator Foot (SM base).

100 position terminal pins (MGA, Mini-grid Array) to solder balls. Surface mounts to target BGA land pattern.

	<b>SF-BGA100A-B-11 Drawing</b> © 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Status: Released	Scale -	Rev: A	
		Drawing: B. Roux		Date:10/21/04	
		File: SF-BGA100A-B-11 Dwg.mcd		Modified:	

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.